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U.S. DEPARTMENT OF COMMERCE U.S. Patent and Trademark Office

OMB No. 0651-0027 (exp. 5/31/2002)		
To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof		
Name of conveying party(ies):	2. Name and address of receiving party(ies)	
Hitoshi Ebihara and Yuichi Nakamura	Name: Sony Computer Entertainment Inc.	
	Internal Address:	
<u></u>	Street Address:	
Additional name(s) of conveying party(ies) Yes X No attached?	1-1, Akasaka 7-chome Minato-ku	
3. Nature of Conveyance:		
x Assignment Merger		
Security Agreement Change of Name	City: Tokyo	
Other	State: Japan Zip: 107-0052	
Execution Date: December 17, 2001	Additional name(s) & Yes x No address(es) attached:	
4. Application number(s) or patent number(s):		
If this document is being filed together with a new application, the exe	ecution date of the new application is:	
A. Patent Application No.(s):	B. Patent No.(s):	
09/974,608	JAN 19 2002	
Additional numbers attache	ed? Yes x No	
Name and address of party to whom correspondence concerning document should be mailed:	6. Total number of applications and patents involved:1	
Name: Robert B. Cohen LERNER, DAVID, LITTENBERG, KRUMHOLZ & MENTLIK, LLP	7. Total fee (37 CFR 3.41) \$ 40.00	
Internal Address:	Enclosed	
Street Address: 600 South Avenue West	X Authorized to be charged to deposit account	
	8. Deposit account number:	
	12-1095	
City: State: Zip: Westfield NJ 07090	(Attach duplicate copy of this page if paying by deposit account)	
DO NOT USE	THIS SPACE	
9. Statement and signature.		
To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.		
Robert B. Cohen Name of Person Signing	ignature January 9, 2002 Date	
Total number of pages including cover sheet, attachments, and documents: 3		

02/14/2002 DBYRNE 00000015 121095 09974608 01 FC:581 40.00 CH

Docket Number: SCEI 3.0-090 SCEI Ref. No.: WSC-128-US-00

ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in:

DATA PROCESSING SYSTEM AND METHOD, COMPUTER PROGRAM, AND RECORDING MEDIUM

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Computer Entertainment Inc., a Japanese corporation with offices at 1-1, Akasaka 7-chome, Minato-ku, Tokyo 107-0052, Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in forcign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the application number and filing date of this application in the spaces that follow: Application Number: 09/974,608, Filing Date: October 10, 2001.

This assignment executed on the dates indicated below.

Hitoshi Ebihara Name of First or Sole Inventor	Execution Date of U.S. Patent Application
KANAGAUM, Japan Residence of First or Sole Inventor	
Mitadu Shihaya Signature of First or Sole Inventor	14 Pec 200/ Date of this Assignment

PATENT REEL: 012567 FRAME: 0862

Docket Number: SCEI 3.0-090 SCEI Ref. No.: WCS-128-US-00

Yuichi Nakamura	
Name of Second Joint Inventor	Execution Date of U.S. Patent Application
Tokyo , Japan Residence of Second Joint Inventor	
Residence of Second Joint Inventor	
Signature of Second Joint Inventor	17 Dec 2001
Signature of Second Joint Inventor	Date of this Assignment
Name of Third Joint Inventor	Execution Date of U.S. Patent Application
Residence of Third Joint Inventor	
Signature of Third Joint Inventor	Date of this Assignment
Name of Fourth Joint Inventor	Execution Date of U.S. Patent Application
Residence of Fourth Joint Inventor	
Signature of Fourth Joint Inventor	Date of this Assignment
Name of Fifth Joint Inventor	Execution Date of U.S. Patent Application
Residence of Fifth Joint Inventor	
Signature of Fifth Joint Inventor	Date of this Assignment

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RECORDED: 01/29/2002

PATENT REEL: 012567 FRAME: 0863